

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1 through 8. (canceled).

9. (currently amended) A coating method of forming a coating film on a surface of a substrate by making a coating liquid which is raised by capillary phenomenon in a nozzle contact with the surface and making the raised coating liquid be coated on the surface by the relative movement of the nozzle and the substrate,

comprising:

holding the substrate by a holding means so that the surface to be coated by the coating liquid faces downward;

bringing the holding means and a chucking means toward each other by moving at least one of the holding means and the chucking means, maintaining the surface to be coated facing downward;

chucking the substrate by the chucking means;

separating the holding means and ~~a~~the chucking means away from each other by moving at least one of the holding means and the chucking means; and

forming the coating film on the surface to be coated of the substrate by moving at least one of the nozzle and the chucking means in a horizontal direction,

wherein, when ~~attaching and detaching~~ the substrate is attached to and from the holding means, the holding means is in an inclined state and turns by a predetermined angle to make the substrate held in a horizontal state, and when the substrate is to be detached from the holding means, the holding means is in a horizontal state and turns by the predetermined angle to make the substrate held in an inclined state,

said holding means being capable of being separated from said chucking means in order that a mechanism for turning the substrate, which is provided with the holding means, not influence the positional precision of the chucking means during coating.

10. (previously presented) The coating method of claim 9 wherein, after said forming, the substrate is released from the chucking means in a state that a coated surface of the substrate faces downward.

11. (previously presented) The coating method of Claim 9 wherein the chucking is carried out by vacuum means.

12. (previously presented) The coating method of Claim 9 wherein during the forming of the coating film on the surface, controlling a distance between the nozzle and the surface so that the film thickness is uniform.

13. (previously presented) The coating method of Claim 9 wherein before said forming, the nozzle is lifted so that the coating liquid is brought into contact with the surface, and the nozzle is descended an amount to determine a coating thickness.

14. (canceled).

15. (previously presented) The coating method of claim 9, wherein the coating film comprises a photo-resist.

16. (previously presented) The coating method of claim 9, wherein the substrate comprises a photo mask blank.

17. (currently amended) A method of manufacturing a photo mask blank having a photo resist coating film on a surface, which film is formed, on a substrate, by making a coating liquid which is raised by capillary phenomenon in a nozzle contact with the surface and making the raised coating liquid be coated on the surface by the relative movement of the nozzle and the substrate,

the method comprising:

holding the substrate by a holding means so that the surface to be coated by the coating liquid faces downward;

bringing the holding means and a chucking means toward each other by moving at least one of the holding means and the chucking means, maintaining the surface to be coated facing downward;

chucking the substrate by the chucking means; ~~and~~

separating the holding means and the chucking means away from each other by moving at least one of the holding means and the chucking means; and

forming the coating film on the surface to be coated of the substrate by moving at least one of the nozzle and the chucking means in a horizontal direction,

wherein, when ~~attaching and detaching~~ the substrate is attached to and from the holding means, the holding means is in an inclined state and turns by a predetermined angle to make the substrate held in a horizontal state, and when the substrate is to be detached from the holding means, the holding means is in a horizontal state and turns by the predetermined angle to make the substrate held in an inclined state,

said holding means being capable of being separated from said chucking means in order that a mechanism for turning the substrate, which is provided with the holding means, not influence the positional precision of the chucking means during coating.

18. (previously presented) The coating method of Claim 9, wherein the substrate is sized so that at least one side has a length of 300 mm.

19. (previously presented) The method of Claim 17, wherein the substrate is sized so that at least one side has a length of 300 mm.

20. (previously presented) The coating method of claim 9, further comprising absorbing shock in the holding means when the holding means and the chucking means are moved in an up-and-down direction with respect to one another.

21. (previously presented) The coating method of claim 17, further comprising absorbing shock in the holding means when the holding means and the chucking means are moved in an up-and-down direction with respect to one another.

22. (currently amended) The method of Claim 9 wherein the holding means turns by a the predetermined angle to make the substrate individually in the inclined state or in the horizontal state~~angle for attaching and detaching the substrate.~~

23. (currently amended) The method of Claim 17 wherein the holding means turns by a the predetermined angle to make the substrate individually in an the inclined state or the horizontal state~~angle for attaching and detaching the substrate.~~

24. (currently amended) A coating method of forming a coating film on a surface of a substrate by making a coating liquid which is raised by capillary phenomenon in a nozzle contact with the surface and making the raised coating liquid be coated on the surface by the relative movement of the nozzle and the substrate,

said coating method is carried out with a coating apparatus comprising:

holding means for holding the substrate so that the surface to be coated by the coating liquid faces downward; ~~said holding means having a~~

chucking means for receiving the substrate from the holding means by chucking the substrate in a state that the surface of the substrate to be coated faces downward,

coating means having a nozzle for coating a film on the surface of the substrate in a state of being chucked, and

moving means for moving at least one of the nozzle and the chucking means in a horizontal direction during coating,

said holding means being provided with a turning means for turning the substrate, which is in an inclined state, by a predetermined angle to a horizontal state when the substrate is attached to the holding means, and for turning the substrate which is in a horizontal state by the predetermined angle to make the substrate held in an inclined state when the substrate is to be detached, ~~for attaching and detaching the substrate to and from the holding means,~~

said holding means being capable of being separated from said chucking means in order that ~~a~~ the turning means not influence the positional precision of the chucking means during coating.

25. (previously presented) The coating method of claim 24, wherein the coating film comprises a photo-resist.

26. (currently amended) The method of Claim 24 wherein the holding means turns by a the predetermined angle to make the substrate individually in ~~an~~ the inclined state or in the horizontal state ~~angle for attaching and detaching the substrate.~~